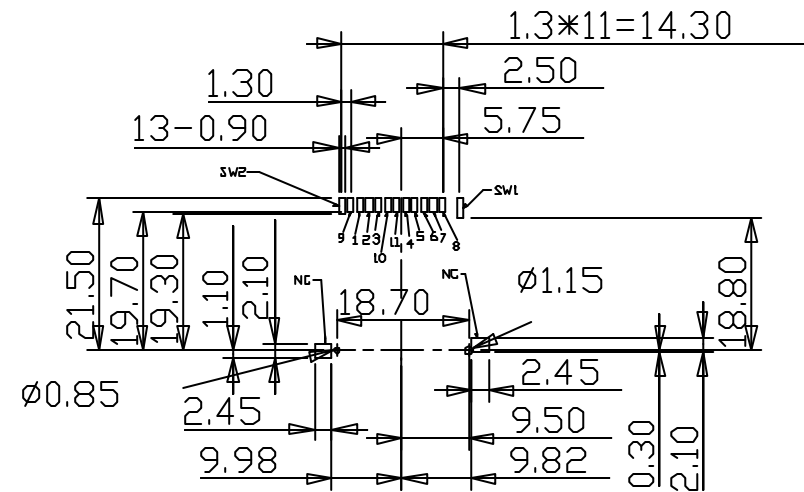
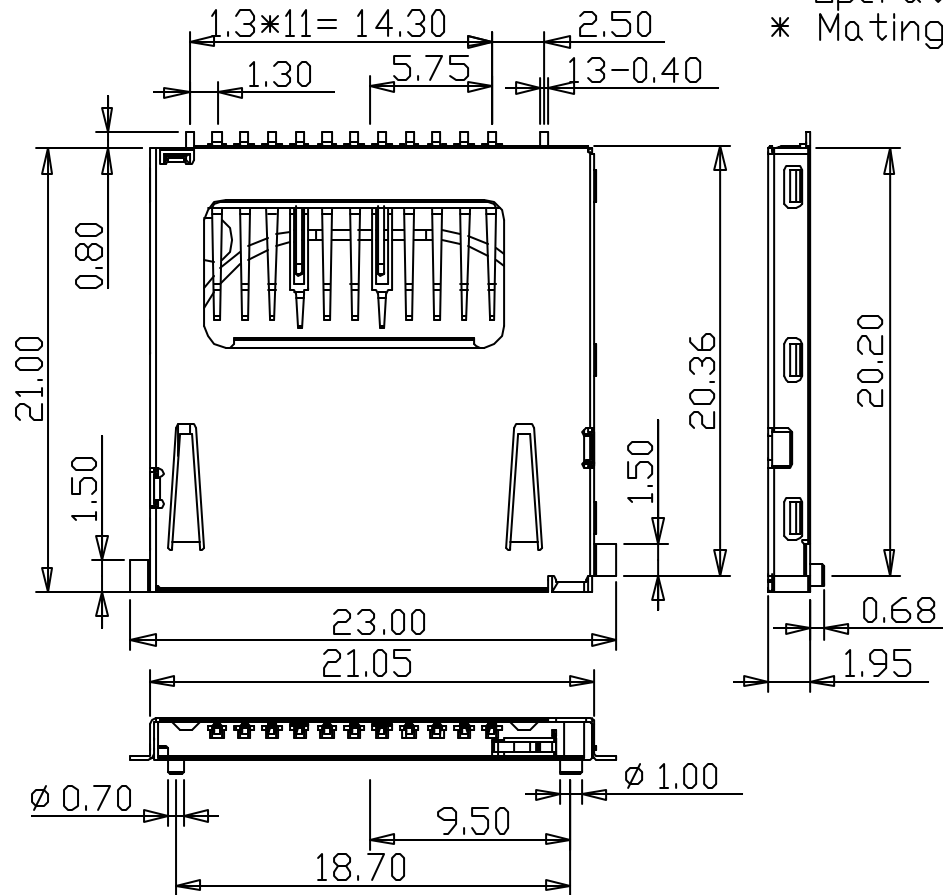


MATERIAL

- * Housing : LCP
- * Contact : Copper alloy
Gold Finish / TIN
- * Cover : Stainless Steel / TIN
- * Switch : Copper Alloy
Area : Gold Finish / TIN

SPECIFICATIONS

- * Insulation Resistance : 1,000 mΩ Min. at 500V DC
- * Withstanding Voltage : 500V AC rms for 1 Minute
- * Contact Resistance : 100 mΩ at 1mA / 20 mV Max.
- * Voltage Rating : 250V rms Ac
- * Current Rating : 0.5A
- * Operating Temp Range : -25°C ~ +85°C
- * Mating Cycles : 10,000 cycles



RECOMMENDED PCB PATTERN LAYOUT



PART NO. **MSDC-W18PA-11**

DWG NO. **MSDC-W18PA-11**

FILE NO.

UNIT / mm

SCALE 1:1

CHECKED BY CY

DRAWING BY

PROJECTION



TOLERANCES ARE

.X ± 0.10

.XX ± 0.05

.XXX ± 0.02

AWG

DESCRIPTION:

MINI-SD CONNECTOR
REVERSE TYPE

AREA

REVISIONS

HK

DATE

煜倫有限公司